



GT25FF120B3H

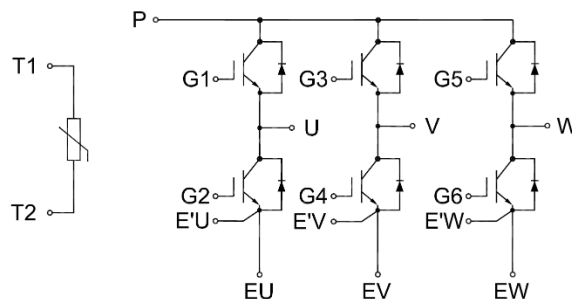
IGBT Module

Preliminary Data

Features:

- Field Stop Trench Gate IGBT
- Short Circuit Rated $>10\mu\text{s}$
- Low Saturation Voltage
- Low Switching Loss
- 100% RBSOA Tested($2\times I_c$)
- Low Stray Inductance
- Lead Free, Compliant with RoHS Requirement

Circuit Diagram



Applications:

- Air Conditioning
- Motor Drives
- Servo Drives
- UPS Systems

IGBT, Inverter

Maximum Rated Values ($T_C=25^\circ\text{C}$ unless otherwise specified)

V_{CES}	Collector-Emitter Blocking Voltage		1200	V
V_{GES}	Gate-Emitter Voltage		± 20	V
I_C	Continuous Collector Current	$T_C=100^\circ\text{C}$	25	A
		$T_C=25^\circ\text{C}$	50	A
I_{CM}	Repetitive Peak Collector Current	$t_P=1\text{ms}$	50	A
P_D	Maximum Power Dissipation per IGBT	$T_C=25^\circ\text{C}$ $T_{Jmax}=175^\circ\text{C}$	280	W



Electrical Characteristics of IGBT ($T_C=25^{\circ}\text{C}$ unless otherwise specified)

Static Characteristics

Symbol	Description	Conditions	Min.	Typ.	Max.	Units
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C=1\text{mA}$, $V_{CE}=V_{GE}$	5.0	5.6	6.5	V
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$I_C=25\text{A}$, $V_{GE}=15\text{V}$	$T_J=25^{\circ}\text{C}$	1.75	2.10	V
			$T_J=125^{\circ}\text{C}$	2.10		
			$T_J=150^{\circ}\text{C}$	2.20		
I_{CES}	Collector-Emitter Leakage Current	$V_{GE}=0\text{V}$, $V_{CE}=V_{CES}$, $T_J=25^{\circ}\text{C}$			1	mA
I_{GES}	Gate-Emitter Leakage Current	$V_{GE}=\pm 20\text{V}$, $V_{CE}=0\text{V}$, $T_J=25^{\circ}\text{C}$			200	nA
C_{ies}	Input Capacitance	$V_{CE}=25\text{V}$, $V_{GE}=0\text{V}$, $f=100\text{kHz}$		1.64		nF
C_{oes}	Output Capacitance			0.44		
C_{res}	Reverse Transfer Capacitance			0.02		

Switching Characteristics

$t_{d(on)}$	Turn-on Delay Time	$V_{CC}=600\text{V}$, $I_C=25\text{A}$, $R_{Gon}=20\Omega$, $V_{GE}=\pm 15\text{V}$, Inductive Load	$T_J=25^{\circ}\text{C}$		57		ns
			$T_J=125^{\circ}\text{C}$		58		
			$T_J=150^{\circ}\text{C}$		62		
t_r	Rise Time	$V_{CC}=600\text{V}$, $I_C=25\text{A}$, $R_{Gon}=20\Omega$, $V_{GE}=\pm 15\text{V}$, Inductive Load	$T_J=25^{\circ}\text{C}$		55		ns
			$T_J=125^{\circ}\text{C}$		58		
			$T_J=150^{\circ}\text{C}$		60		
$t_{d(off)}$	Turn-off Delay Time	$V_{CC}=600\text{V}$, $I_C=25\text{A}$, $R_{Goff}=20\Omega$, $V_{GE}=\pm 15\text{V}$, Inductive Load	$T_J=25^{\circ}\text{C}$		208		ns
			$T_J=125^{\circ}\text{C}$		211		
			$T_J=150^{\circ}\text{C}$		214		
t_f	Fall Time	$V_{CC}=600\text{V}$, $I_C=25\text{A}$, $R_{Goff}=20\Omega$, $V_{GE}=\pm 15\text{V}$, Inductive Load	$T_J=25^{\circ}\text{C}$		76		ns
			$T_J=125^{\circ}\text{C}$		223		
			$T_J=150^{\circ}\text{C}$		225		
E_{on}	Turn-on Switching Loss	$V_{CC}=600\text{V}$, $I_C=25\text{A}$, $R_{Gon}=20\Omega$, $V_{GE}=\pm 15\text{V}$, $di/dt=368\text{A}/\mu\text{s}$ ($T_J=150^{\circ}\text{C}$) Inductive Load	$T_J=25^{\circ}\text{C}$		3.1		mJ
			$T_J=125^{\circ}\text{C}$		3.8		
			$T_J=150^{\circ}\text{C}$		4.1		



E_{off}	Turn-off Switching Loss	$V_{CC}=600V$, $I_C=25A$, $R_{Goff}=20\Omega$, $V_{GE}=\pm 15V$, $du/dt=4543V/\mu s$ ($T_J=150^\circ C$) Inductive Load	$T_J=25^\circ C$		2.1		mJ
			$T_J=125^\circ C$		2.4		
			$T_J=150^\circ C$		2.5		
Q_g	Total Gate Charge	$V_{GE}=+15V \dots -15V$	$T_J=25^\circ C$		400		nC
$R_{G(int)}$	Internal Gate Resistor		$T_J=25^\circ C$		0		Ω
I_{SC}	$V_{CC}=600V$, $V_{GE}=+/-15V$, $T_J=25^\circ C$				100		A
$R_{\theta JC}$	Thermal Resistance: Junction-to-Case (per IGBT)					0.54	$^\circ C/W$

FWD, Inverter

Maximum Rated Values ($T_C=25^\circ C$ unless otherwise specified)

V_{RRM}	Repetitive Peak Reverse Voltage	$T_J=25^\circ C$	1200	V
I_F	Diode Continuous Forward Current		25	A
I_{FM}	Diode Maximum Forward Current	$t_p=1ms$	50	A

Electrical Characteristics of Diode ($T_C=25^\circ C$ unless otherwise specified)

Symbol	Description	Conditions		Min.	Typ.	Max.	Units
V _{FM}	Forward Voltage	I _F =25A	T _J =25℃		1.70		V
			T _J =125℃		1.85		
			T _J =150℃		1.85		
t _{rr}	Reverse Recovery Time	I _F =25A, -di _F /dt=271A/μs(T _J =150℃), V _R =600V, V _{GE} =-15V	T _J =25℃		312		ns
			T _J =125℃		489		
			T _J =150℃		540		
I _{rr}	Peak Reverse Recovery Current		T _J =25℃		16.2		A
			T _J =125℃		19.3		
			T _J =150℃		20.5		
Q _{rr}	Reverse Recovery Charge		T _J =25℃		2.5		μC
			T _J =125℃		4.3		
			T _J =150℃		4.4		



E _{rec}	Reverse Recovery Energy	I _F =25A, -di _F /dt=271A/μs(T _J =150℃), V _R =600V, V _{GE} =-15V	T _J =25℃		0.7		mJ
			T _J =125℃		1.4		
			T _J =150℃		1.5		
R _{θJC}	Diode Thermal Resistance: Junction-to-Case(per Leg)					0.97	℃/W

Internal NTC-Thermistor Characteristics

Symbol	Conditions	Min.	Typ.	Max.	Units
R ₂₅	T _C =25°C		5		kΩ
ΔR/R	T _C =100°C, R ₁₀₀ =465Ω	-5		+5	%
P ₂₅	T _C =25°C			10	mW
B _{25/50}	$R_2=R_{25} \exp[B_{25/50}(1/T_2-1/(298.15K))]$		3380		K
B _{25/80}	$R_2=R_{25} \exp[B_{25/80}(1/T_2-1/(298.15K))]$		3440		K
B _{25/100}	$R_2=R_{25} \exp[B_{25/100}(1/T_2-1/(298.15K))]$		3545		K

Module

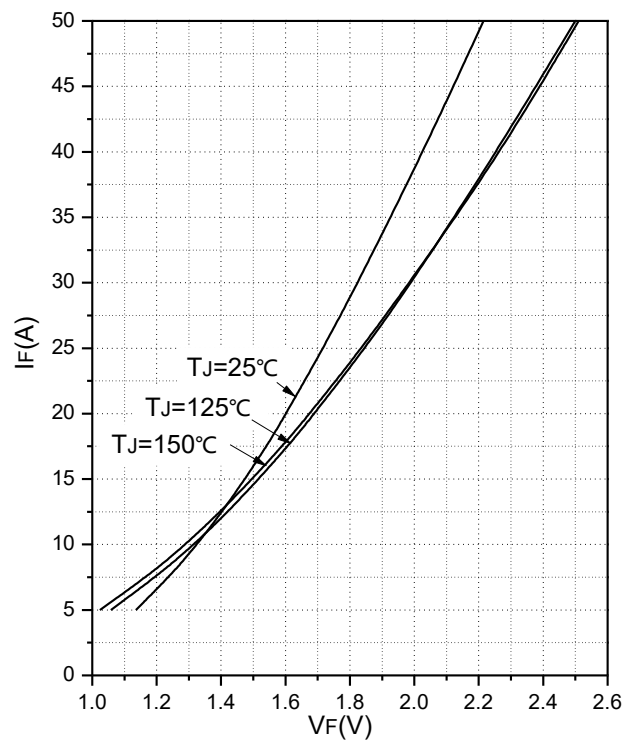
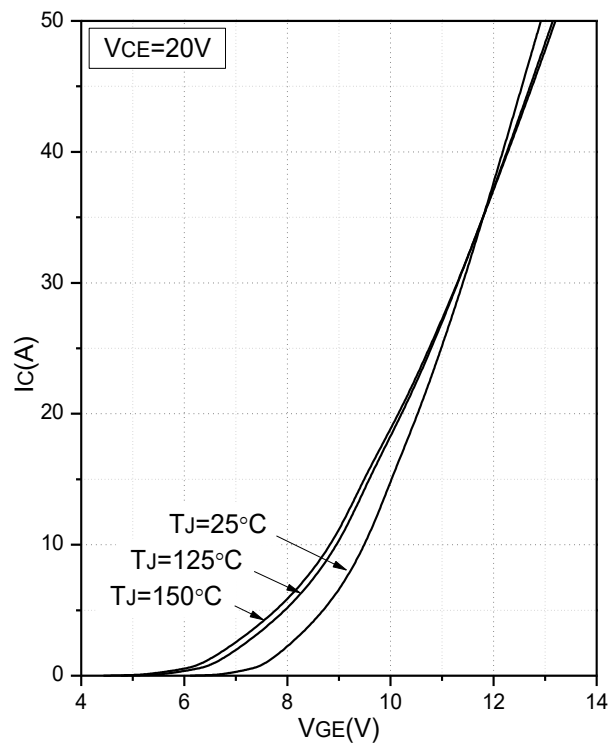
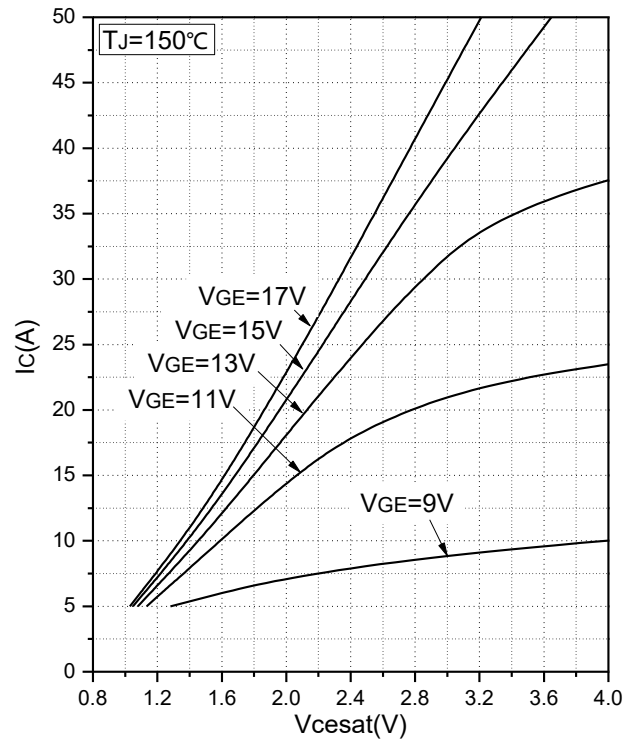
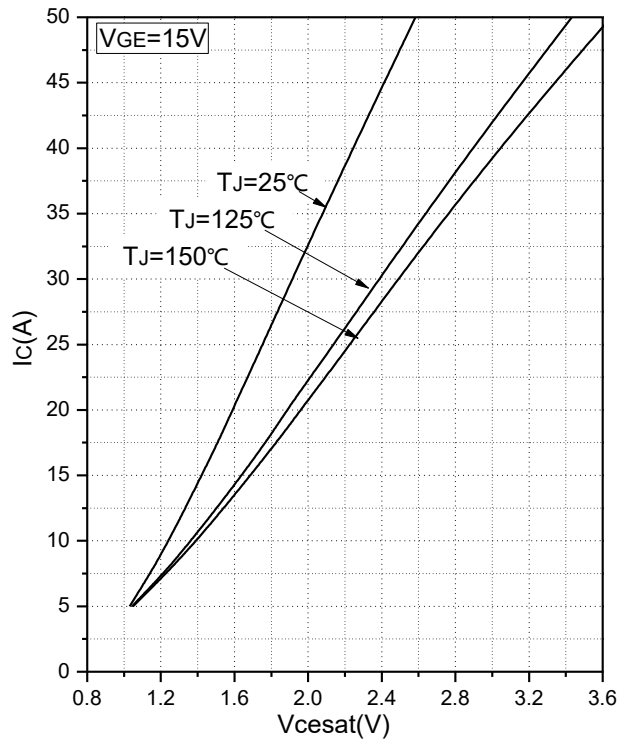
Symbol	Description		Min.	Typ.	Max.	Units
V _{iso}	Isolation Voltage (All Terminals Shorted)	RMS, f=50Hz, 1minute	2500			V
T _J	Maximum Junction Temperature				175	°C
T _{JOP}	Maximum Operating Junction Temperature Range		-40		+150	°C
T _{stg}	Storage Temperature		-40		+125	°C
CTI	Comparative Tracking Index		200			
R _{θCS}	Case-to-Sink Thermally (Conductive Grease Applied)				0.08	°C/W
T	Mounting Screw:M4		1.5		1.8	N·m
G	Weight			23		g



Ordering Information Table

Device code	G	T	25	FF	120	B3	H
	①	②	③	④	⑤	⑥	⑦

- ① - IGBT Module
- ② - Trench, Low Switching Losses IGBT
- ③ - Rated Current (25=25A)
- ④ - Circuit Configuration (Full Bridge)
- ⑤ - Rated Voltage (120=1200V)
- ⑥ - Package Type
- ⑦ - Test Level (Pass the Important Reliability Test-Industrial Grade)



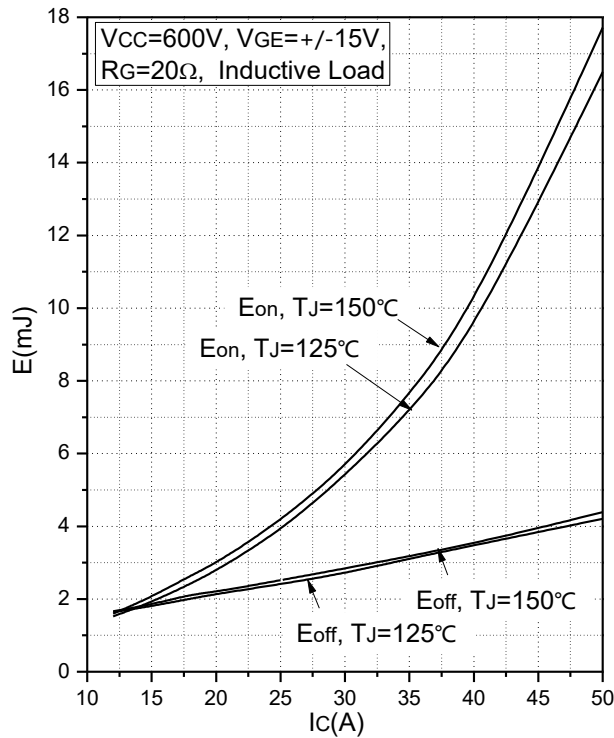


Fig.5 Typical Switching Loss vs. Collector Current

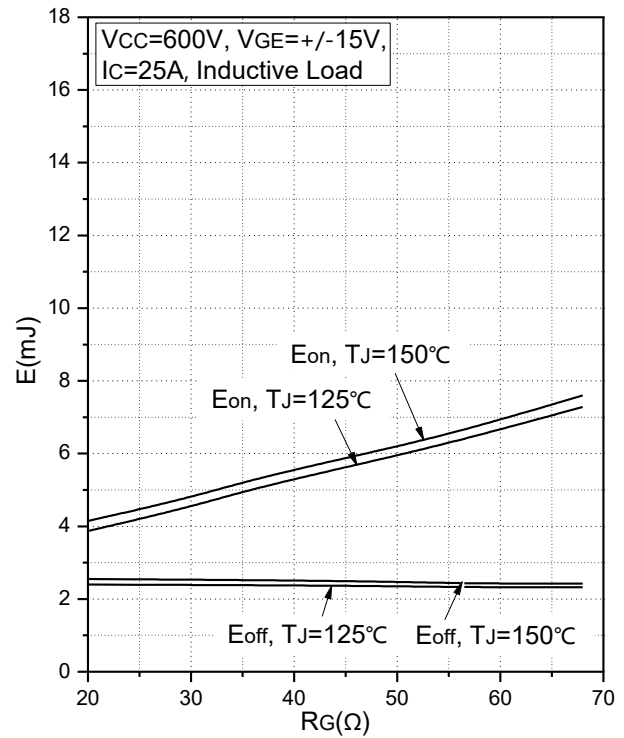


Fig.6 Typical Switching Loss vs. Gate Resistance

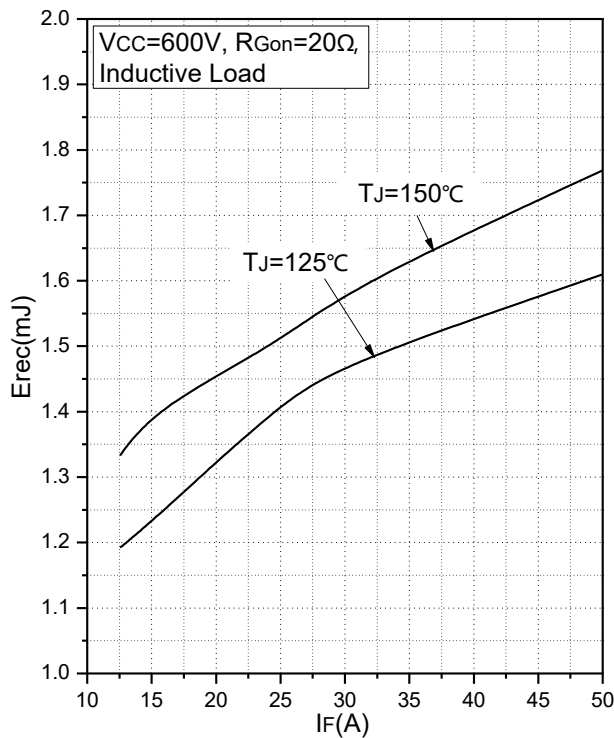


Fig.7 Typical Switching Loss vs. Forward Current

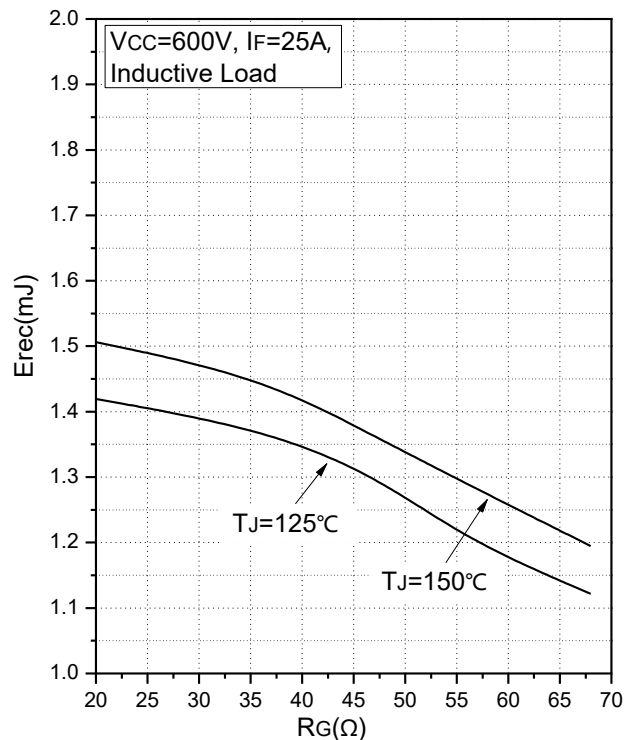


Fig.8 Typical Switching Loss vs. Gate Resistance

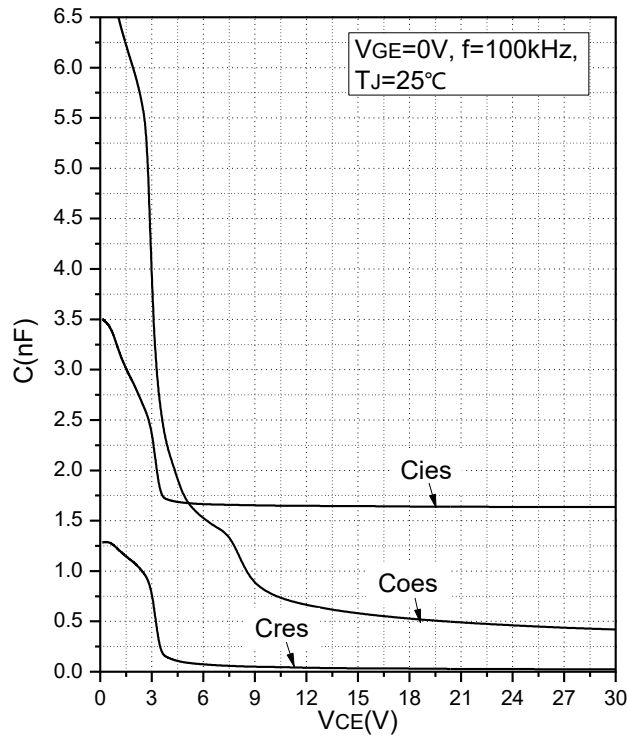


Fig.9 Capacitance Characteristics

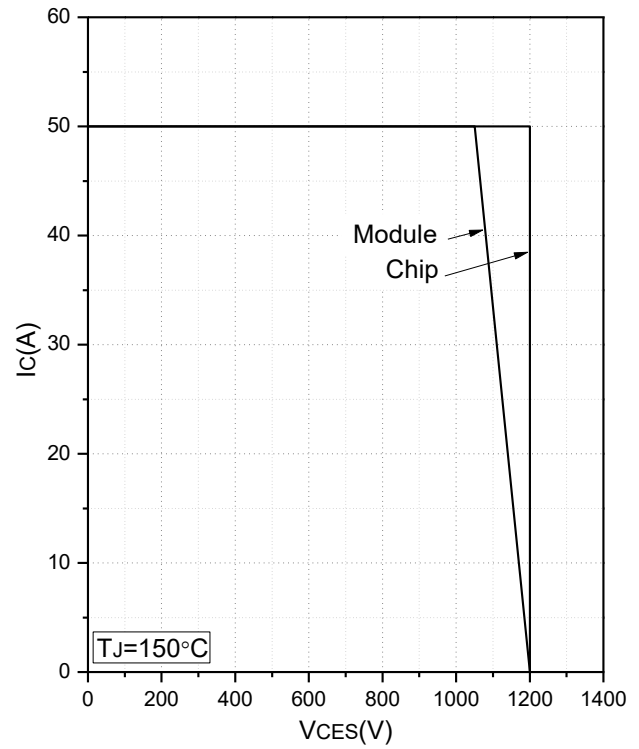


Fig.10 Reverse Bias Safe Operation Area

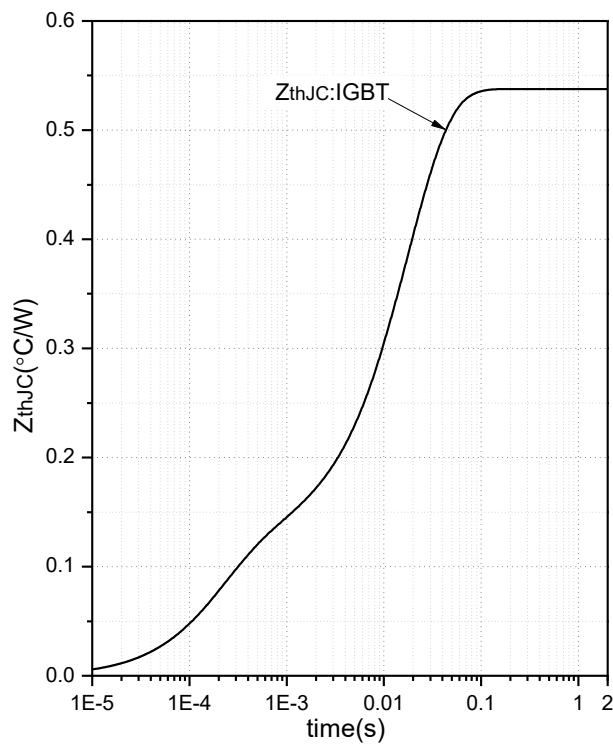


Fig.11 Transient Thermal Impedance IGBT

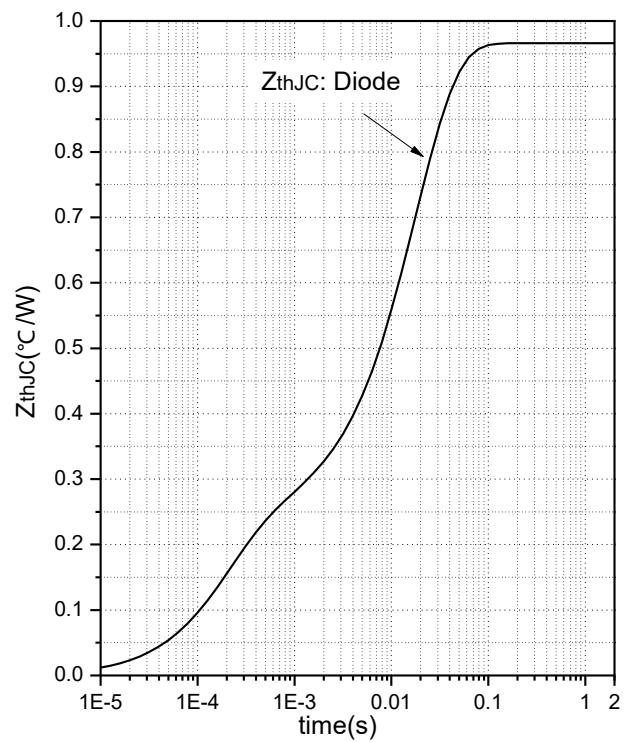


Fig.12 Transient Thermal Impedance Diode

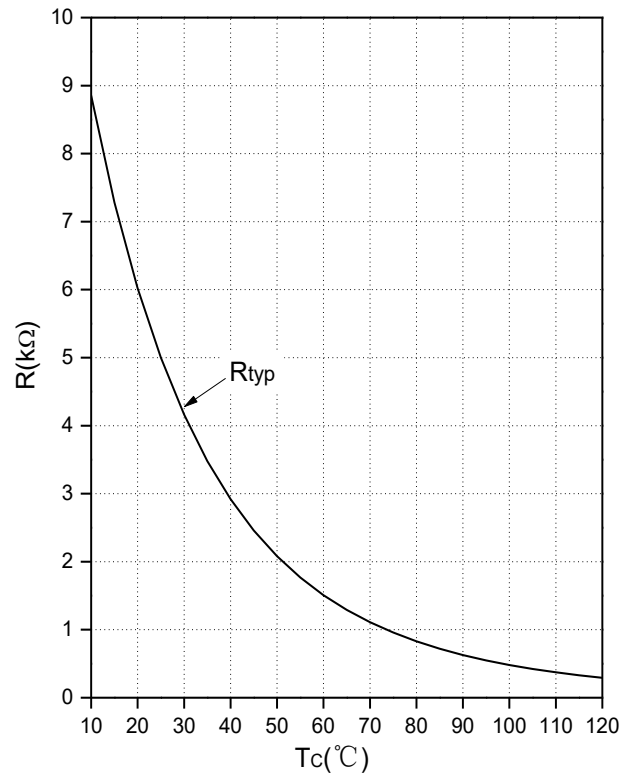
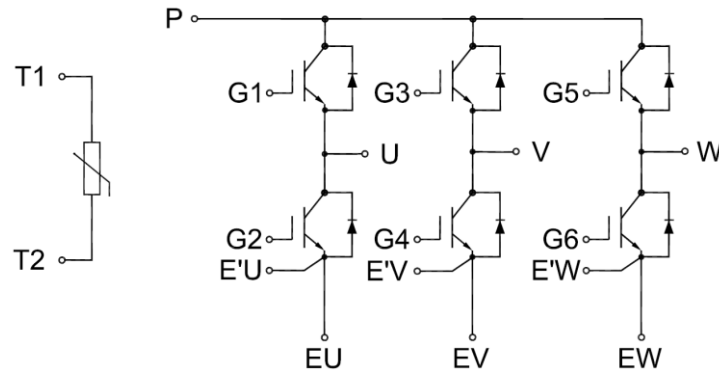


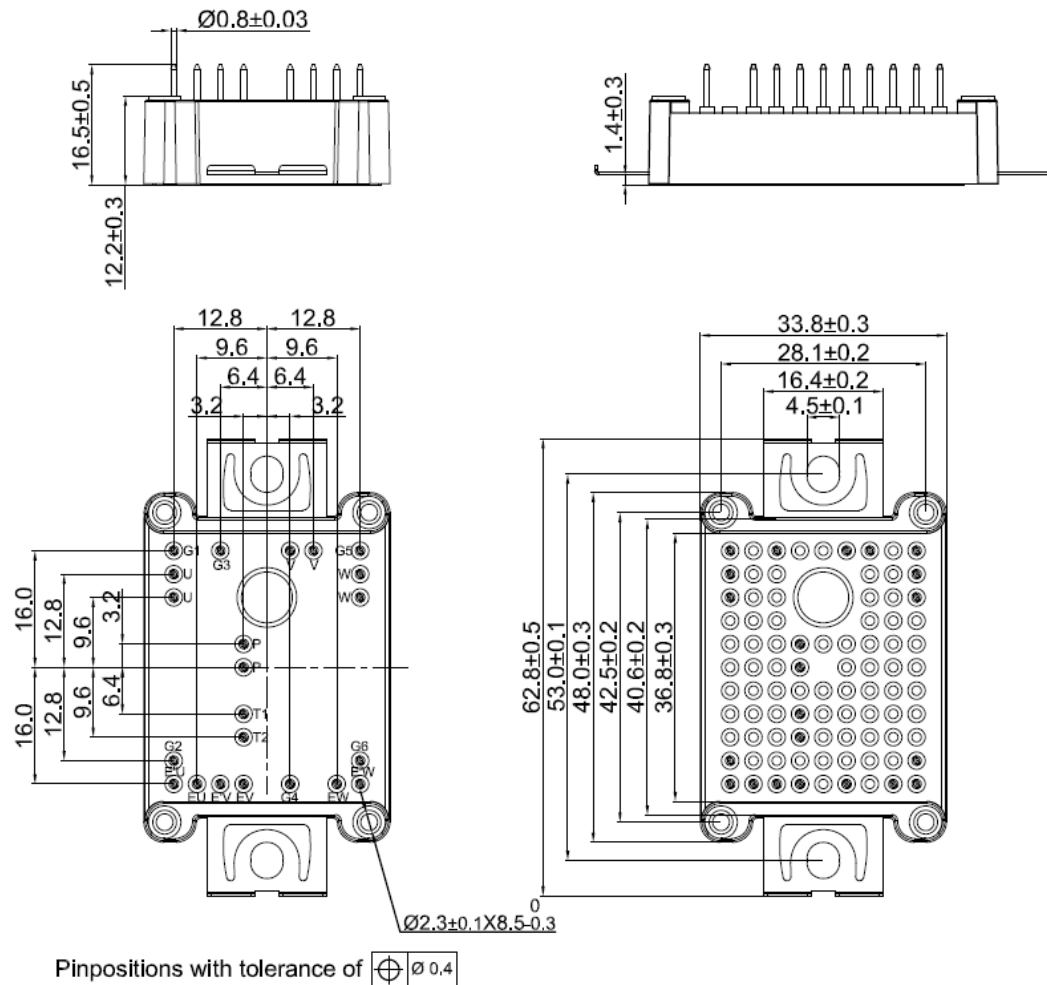
Fig.13 NTC Temperature Characteristics



Internal Circuit



Package Outline (Unit: mm):





Revision	Notes
01	Initial Release

Announcement

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